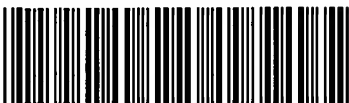


**Search Notes**

Application No.

10/603,976

Examiner

Stephen W. Smoot

Applicant(s)

JUNG ET AL.

Art Unit

2813

**SEARCHED**

Class	Subclass	Date	Examiner
438	637	7/19/2004	SWS
438	675	7/19/2004	SWS
438	684	7/19/2004	SWS
438	692	7/19/2004	SWS
438	693	7/19/2004	SWS
252	79.1	7/19/2004	SWS
252	79.2	7/19/2004	SWS

*S.W.S.***INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES  
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: CMP - Chemical Mechanical Polishing, Perchloric Acid, Chloric Acid, Hypochlorous Acid,	7/19/2004	<i>S.W.S.</i> SWS
Bromic Acid, Perbromic Acid, Iodic Acid, Periodic Acid, Hard Pad;	7/19/2004	<i>S.W.S.</i> SWS
Wordline - Polysilicon, Nitride Mask, Spacer, Contact Hole, Interlayer - BPSG, FSG, USG, PSG, TEOS.	7/19/2004	<i>S.W.S.</i> SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	7/19/2004	<i>S.W.S.</i> SWS